Subject: Re: Speaker Voice Coil Cooling System Valve - Initial Tests Posted by Wayne Parham on Wed, 29 Jun 2005 17:28:09 GMT

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I was thinking along the same lines. The conductive paste material between transistor and heat sink comes to mind. We'll use a pressed-fit aluminum vent and drill it with several capillary holes. It fits snugly in the center pole, so conductive heat transfer is good. The one we already have worked very well to introduce unidirectional airflow, and now we want to augment this with improved thermal conductivity from the center pole. I'm extremely encouraged with our progress so far.